

From the ILC250 Vertex Detector toward Higgs Physics at FCCee

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Contents

- General Remarks on a Vertex Detector suited to a Higgs Factory
- Case of ILC: Physics oriented requirements and Running conditions
- ILC vertex detector: Achievements & Prospects
- Extension to FCCee vertex detector
- Summary & Conclusions

see also: [A. Besson \(talk at FCC workshop, CERN, January 2020\)](#)

Acknowledgement : [A. Besson \(IPHC-Strasbourg\)](#), [R. Poeschl \(IJCLab-Orsay\)](#)

Role of Vertex Detector for a Higgs Factory

- DISPLACED VERTEX RECONSTRUCTION AND CHARACTERISATION :
 - reconstruction of collision point
 - reconstruction of D-meson and τ -lepton vertices
 - reconstruction of b-quark decays in (top-quark) jets
 - determination of displaced vertex electrical charge
 - etc.
- ROLE IN THE TRACKING :
 - track seeding (depending on main tracker)
 - low P_t track reconstruction
 - track momentum determination (in particular low P_t)
 - fake tracks mitigation (E_{miss} determination)

Generic Vertex Detector Requirements for a Higgs Factory

complete geometrical coverage extending to lowest possible polar angle

exquisite spatial resolution

extremely modest material budget

excellent alignment capability

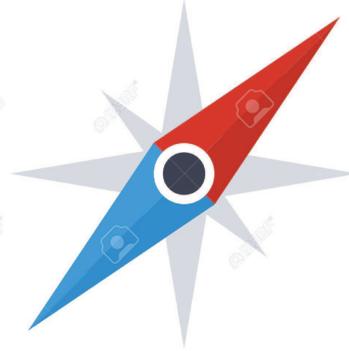
**time stamping against
beam related background**

**sufficient heat removal
from active elements**

**compliance with beam
induced EM perturbations**

inner layer very close to IP

very good link to surrounding tracking systems



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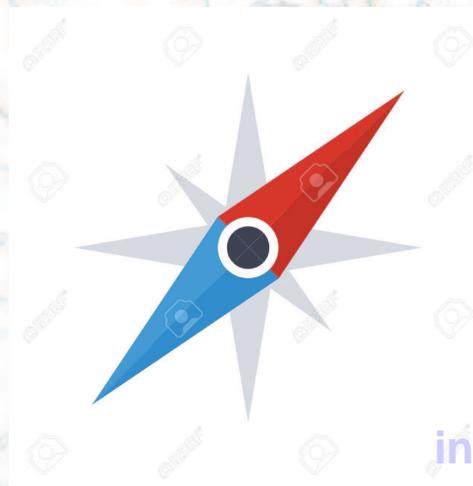
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CHALLENGE: FIND A PASSAGE THROUGH NUMEROUS OBSTACLES COMPOSING A LANDSCAPE OF ANTAGONISTIC CONSTRAINTS AND OBJECTIVES



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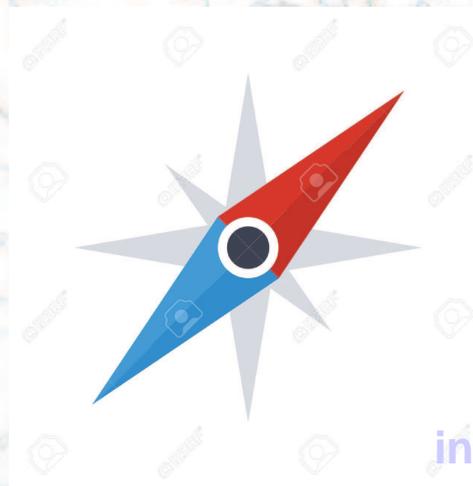
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NEED: EXTENSIVE R&D AND SOPHISTICATED SOFTWARE TOOLS TO DETERMINE
COLLIDER SPECIFIC TRADE-OFFS !



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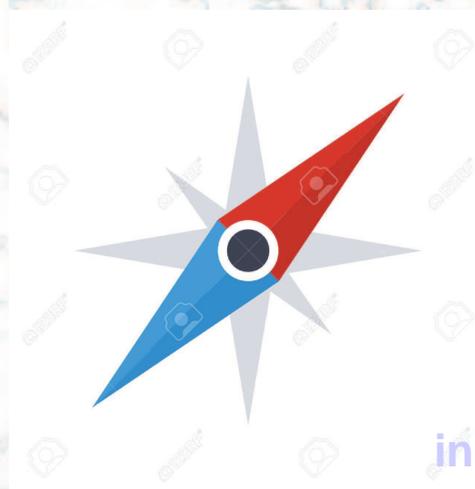
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BONUS OF TIME: EVOLUTION OF INDUSTRIAL TECHNOLOGY MAY MITIGATE SOME OBSTACLES



Major Aspects of the ILC Detector Concepts

- 2 DETECTOR CONCEPTS :

- * SiD: full silicon tracker (most compact)
- * ILD: gaseous main tracker (TPC)

- PRIORITY: GRANULARITY & SENSITIVITY

- EXPLOIT COLLIDER SPECIFICITIES:

- * e^+e^- collisions:

- precisely known collision conditions (E_{cm} , Pol., Lumi.)
- suppressed QCD background \Rightarrow moderate radiation level
H occur in 1% of coll. (LHC: 1 H for 10^{10} collisions)
 \Rightarrow triggerless data taking adapted to faint & rare phenomena

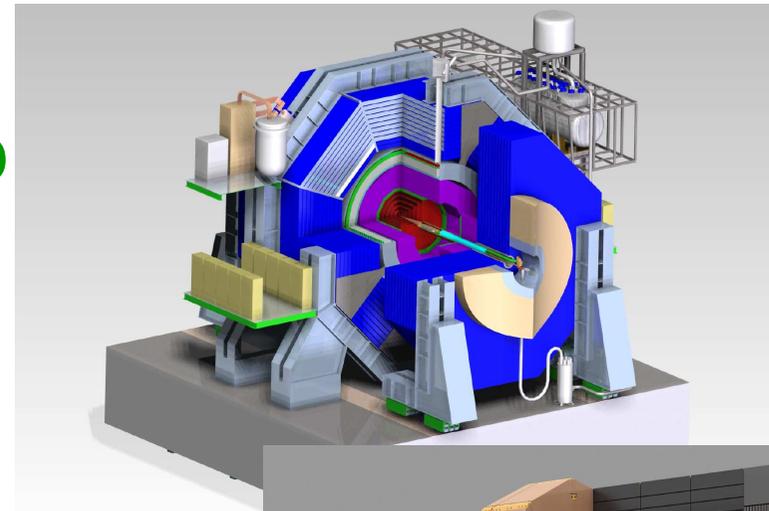
- * beam time structure:

- \lesssim 1% duty cycle \Rightarrow power cycling \equiv saving \Rightarrow allows high granularity
- \gtrsim 300 ns bunch separation \Rightarrow moderate Δt required

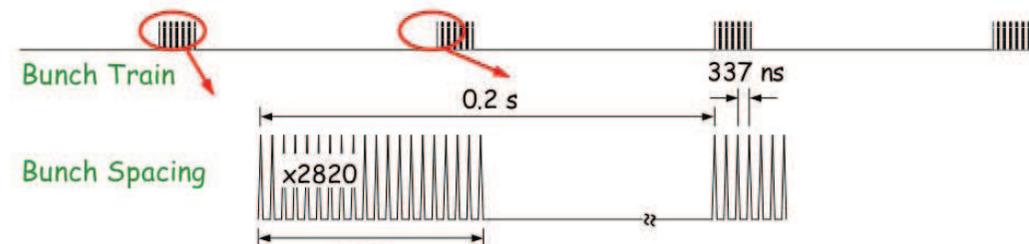
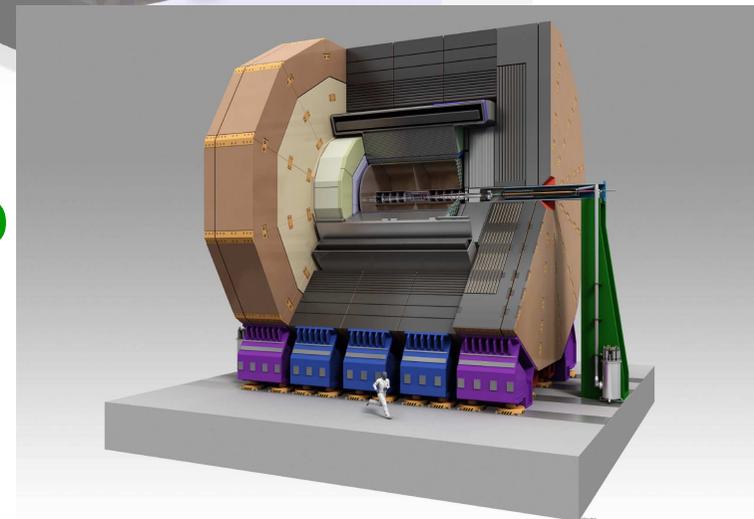
- AMBITIONNED PERFORMANCE HIGHLIGHTS:

- * $\Delta_{2ryVx} < 10 \mu m$
- * charged track rec.: $\Delta(1/p) = 2 \cdot 10^{-5} \text{ GeV}^{-1}$
 $Q_{2ryVx} \Rightarrow$ rec. $P_t \lesssim 100 \text{ MeV}$ tracks
- * mat. budget: $\lesssim 10\% X_0$ in front of calorimetres
- * $\sigma_E^{jet} / E^{jet} \simeq 30\% / \sqrt{E^{jet}}$ (neutral had. !) \Rightarrow PFA

SiD

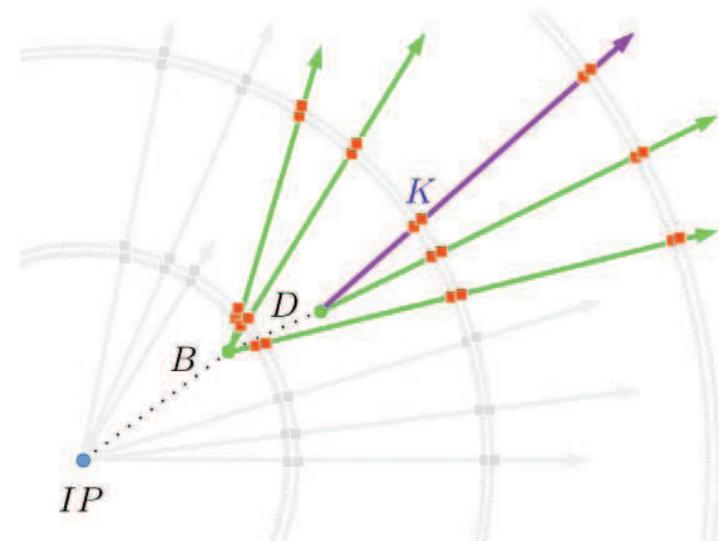


ILD



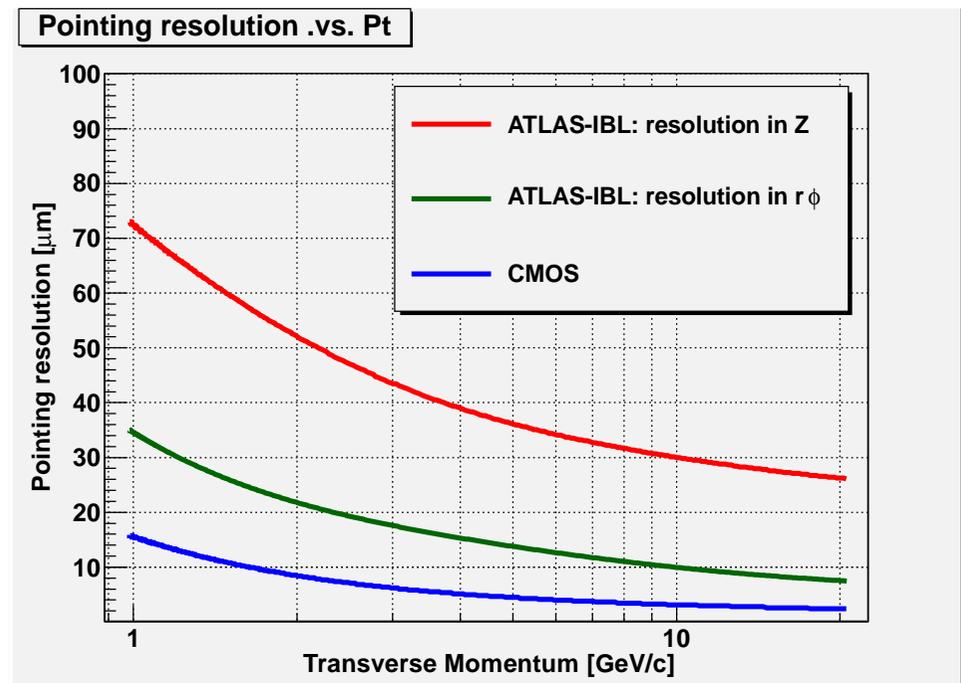
Vertex Detector Performance Goals

- Vertex detector requirements governed by physics oriented parameters rather than running conditions
 - * emphasis on granularity & material budget (very low power)
 - * much less demanding running conditions than at LHC
 - ⇒ alleviated read-out speed & radiation tolerance requests
 - * ILC duty cycle $\gtrsim 1/200$ ⇒ power saving by power pulsing



- Vertexing goal:

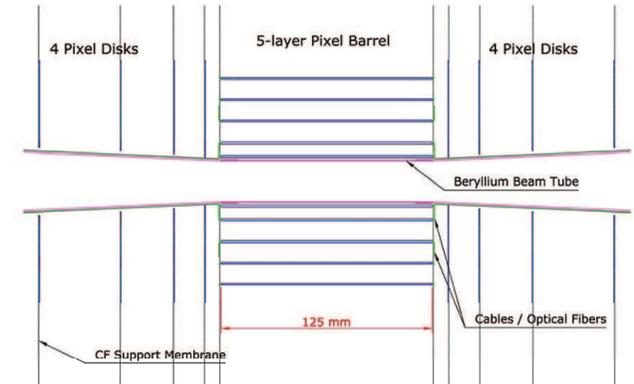
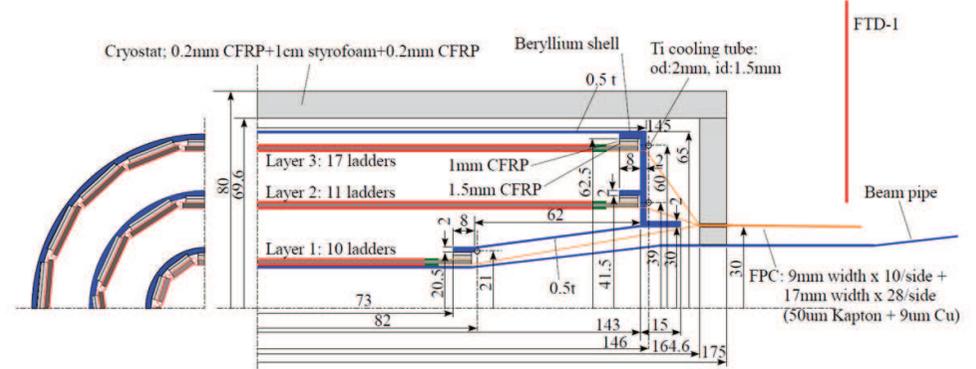
- * achieve high efficiency & purity flavour tagging
 - ↪ charm & tau, jet-flavour !!!
- * reconstruct momentum of soft tracks ($P_t < 100$ MeV)
- * reconstruct displaced vertex charge
- ↪ $\sigma_{R\phi, Z} \leq 5 \oplus 10/p \cdot \sin^{3/2}\theta \text{ } \mu\text{m}$
 - ▷ LHC: $\sigma_{R\phi} \simeq 12 \oplus 70/p \cdot \sin^{3/2}\theta$
- ▷ Comparison: $\sigma_{R\phi, Z}$ (ILD) with VXD
 - made of ATLAS-IBL or ILD-VXD pixels ↪



Vertexing Concepts & Challenges

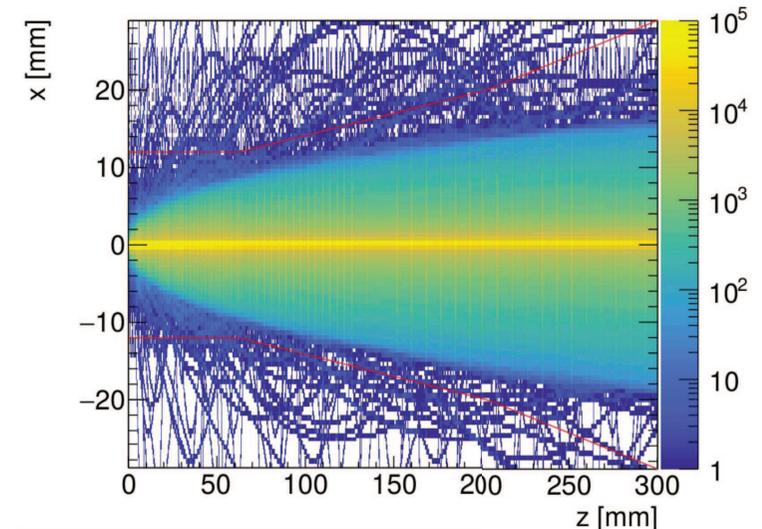
TWO ALTERNATIVE PIXELATED DESIGNS :

- * **ILD**: long barrel of 3 dble layers (R: 16 - 60 mm)
0.3% X_0 / dble layer, $\sigma_{sp} \lesssim 3 \mu m$
- * **SiD**: short barrel of 5 single layers (R: 14 - 60 mm)
0.15% X_0 / layer, $\sigma_{sp} \lesssim 3-5 \mu m$
- * several (small & thin) pixel technology options under development
- * other devts: mat. budget suppression, cooling, 2-sided ladders, ...



RUNNING CONDITIONS DOMINATED BY BEAMSTRAHLUNG E^\pm :

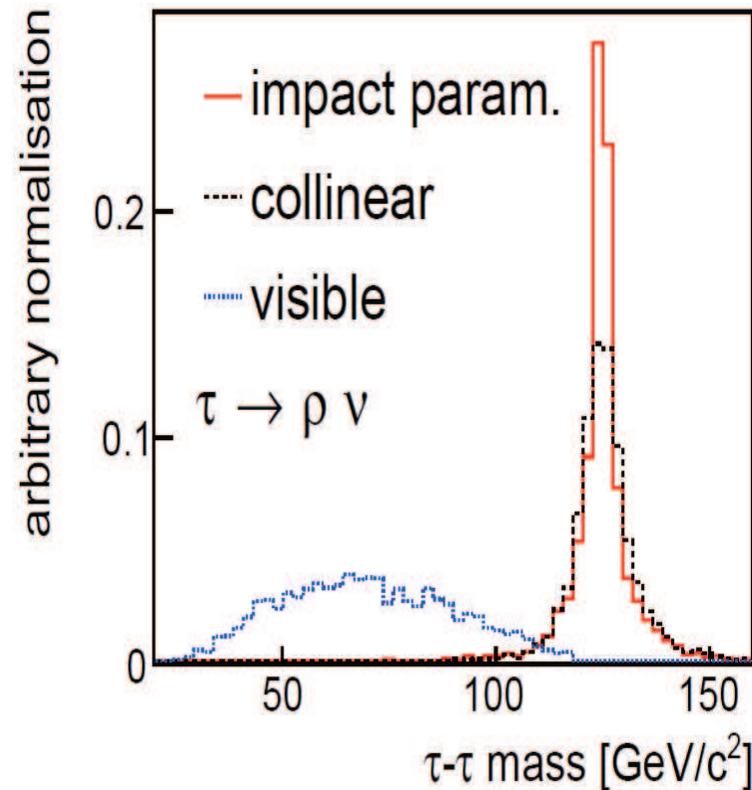
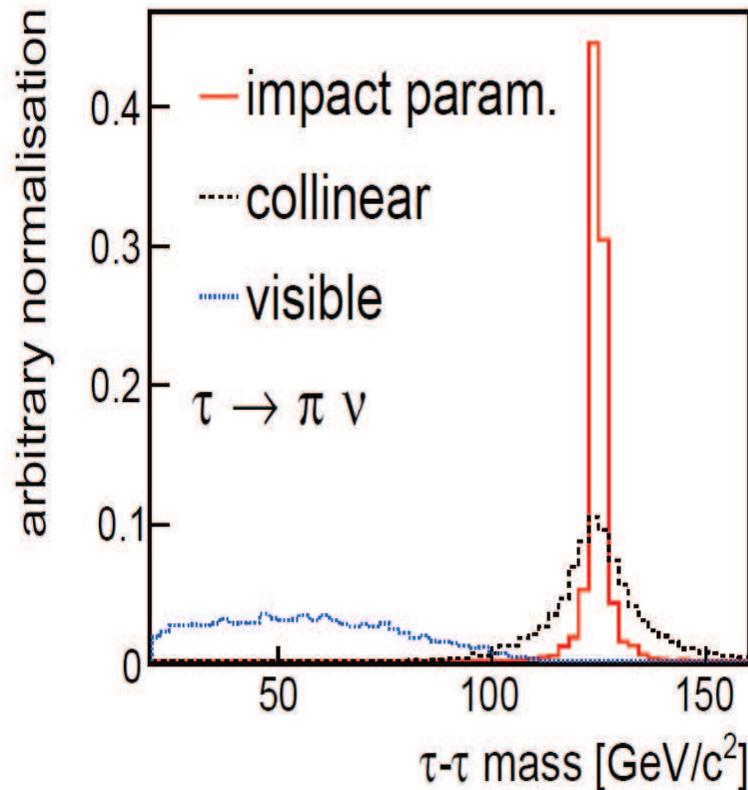
- * Radiation doses: $O(100)$ kRad, $< 10^{12} n_{eq}/cm^2/yr$
- * Rate of e_{BS}^\pm impacts: possibly up to several tens/cm²/BX
 \Rightarrow governs time resolution requirements
- * sizeable uncertainties: σ_{BS} , luminosity
 \Rightarrow substantial safety factors mandatory !



Role of Vertex Detector: Reconstruction of τ lepton

IMPACT OF VERTEX DETECTOR ON τ RECONSTRUCTION: EXAMPLE OF ILD

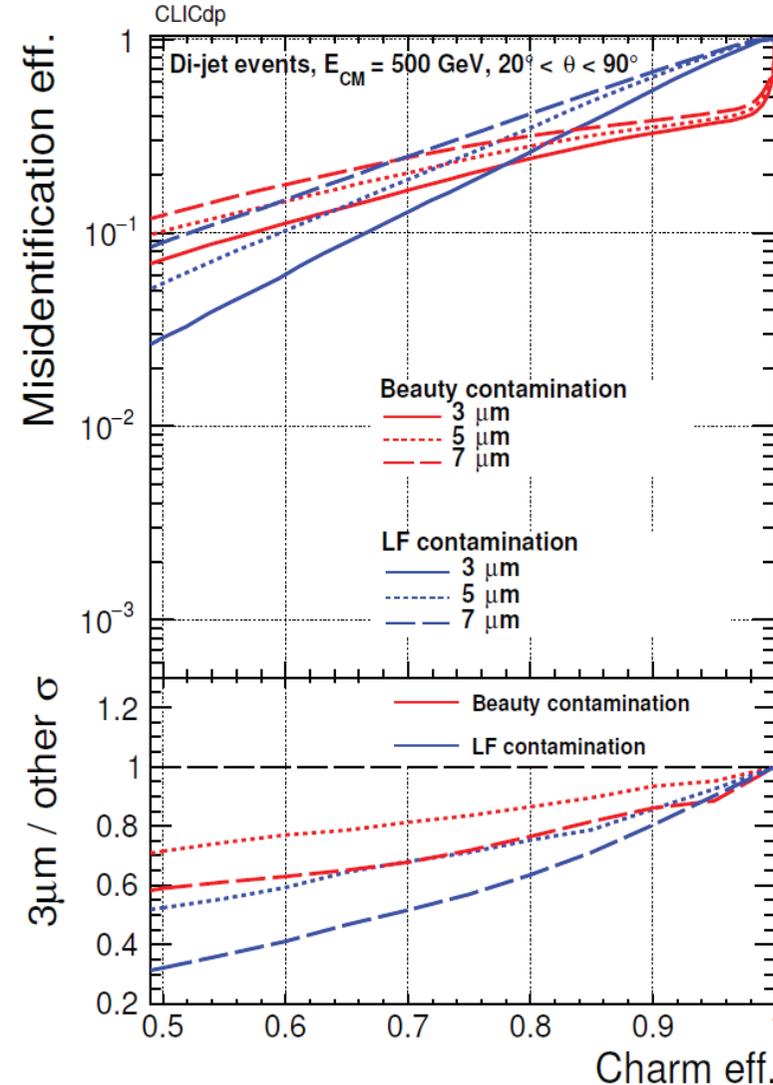
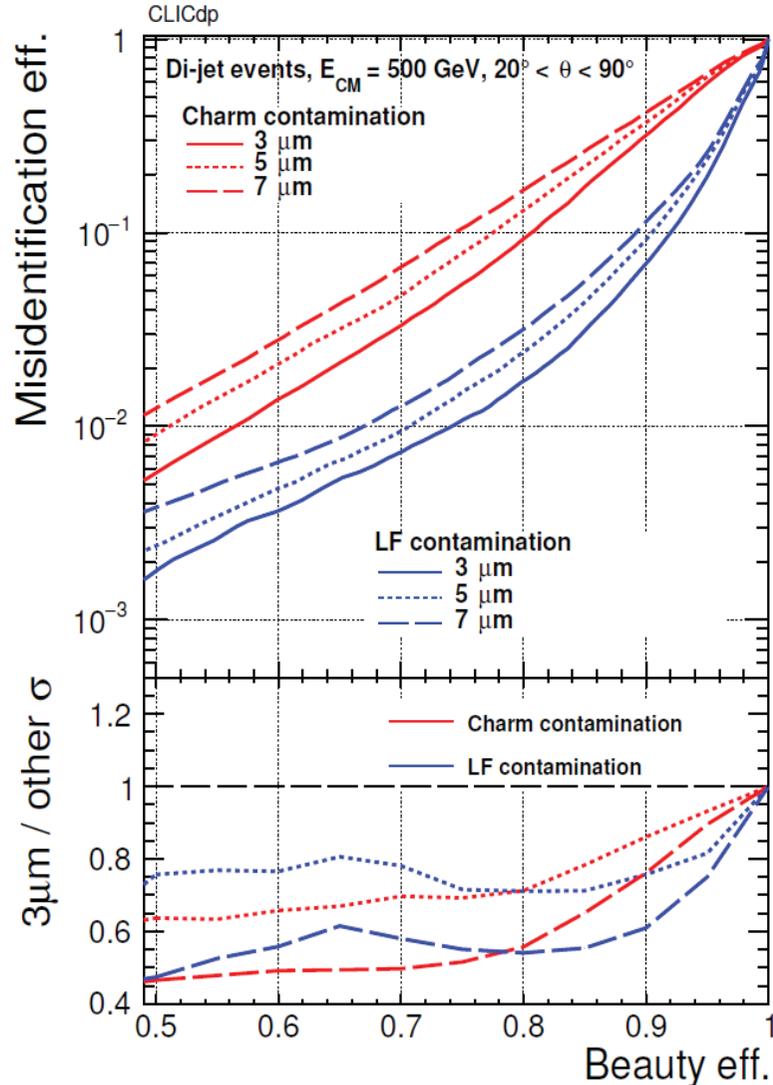
- * use measurements of τ spin state in $e^+e^- \rightarrow ZH \rightarrow \mu^+\mu^-\tau^+\tau^-$ to probe the CP nature of the Higgs boson and search for BSM manifestation by investigating CP conservation in Higgsstrahlung process and Higgs decay
- * concentrate on hadronic decays of τ s (one ν only) using displaced vertex reconstruction



* D. Jeans, Nucl. Instrum. Meth. A810, 51 (2016), arXiv:1507.01700 [hep-ex]

* D. Jeans and G. Wilson, Phys. Rev. D 98, 013007 (2018), arXiv:1804.01241 [hep-ex]

Role of Vertex Detector: Impact of Spatial Resolution on b, c Tagging



- fermion-pair production at $E_{CM} = 500 \text{ GeV}$ (CLICdet vertex detector : $R_{in} = 31 \text{ mm}$)

D. Arominski et al., CLICdp-Note-2018-005, arXiv:1812.07337 [physics.ins-det] (2018)

- $\sigma_{sp} = 7 \mu\text{m} \rightsquigarrow 3 \mu\text{m} \Rightarrow$ contaminations suppressed by $\sim 20\%$ to 40% for 90% tagging efficiency

Monolithic CMOS Pixel Sensors (CPS)

- ILC requirements similar to those of Heavy Ion expts

- ⇒ CPS developed for CBM expt (FAIR/GSI)
- ≡ acts as a forerunner for ILC vertex detectors

- Main characteristics of MIMOSIS

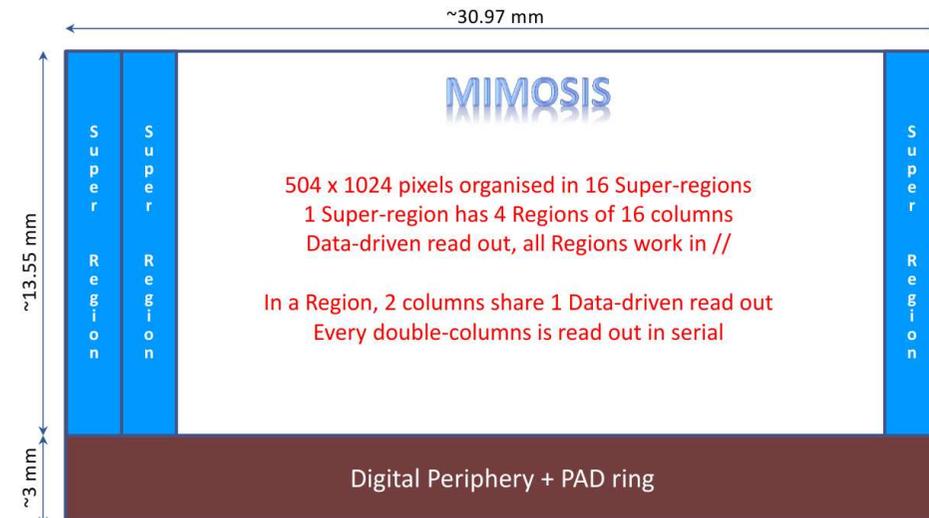
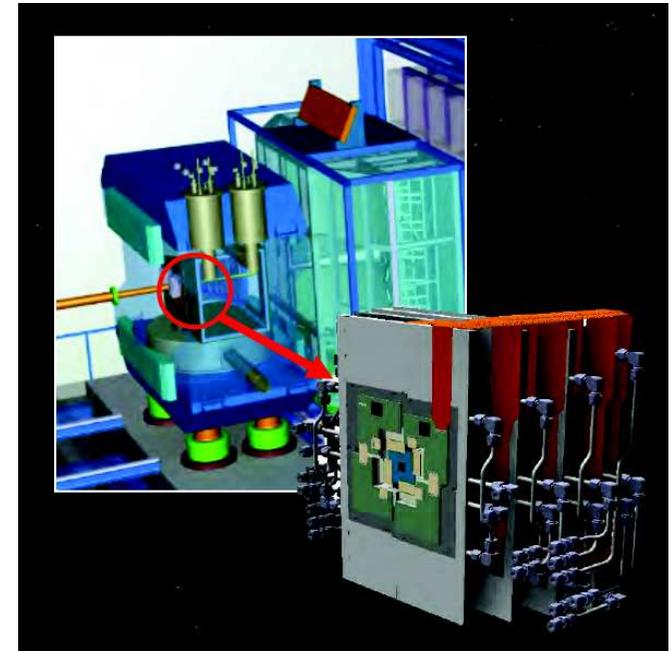
- * TJsc 180 nm imager process with high-res ($25 \mu m$ thick) epitaxy
- * modified high-res ($25 \mu m$ thin) epitaxy ⇒ full depletion
- ⇒ sub-ns charge collection time (+ enhanced rad. tol.)
- * 1024 col. of 504 pixels with asynchronous r.o. (ALPIDE)
- in-pixel discri. with binary charge encoding
- * pixel: $27 \times 30 \mu m^2$ ⇒ $\sigma_{sp} \gtrsim 5 \mu m$ (vs depletion depth)
- * affordable hit density $\simeq 10^8$ hits/cm²/s
- * $\Delta t \sim 5 \mu s$
- * Power density $\sim 40\text{--}50$ mW/cm² (vs hit density)

- Step-1: MIMOSIS-0 proto. ≡ 1/32 slice of final sensor

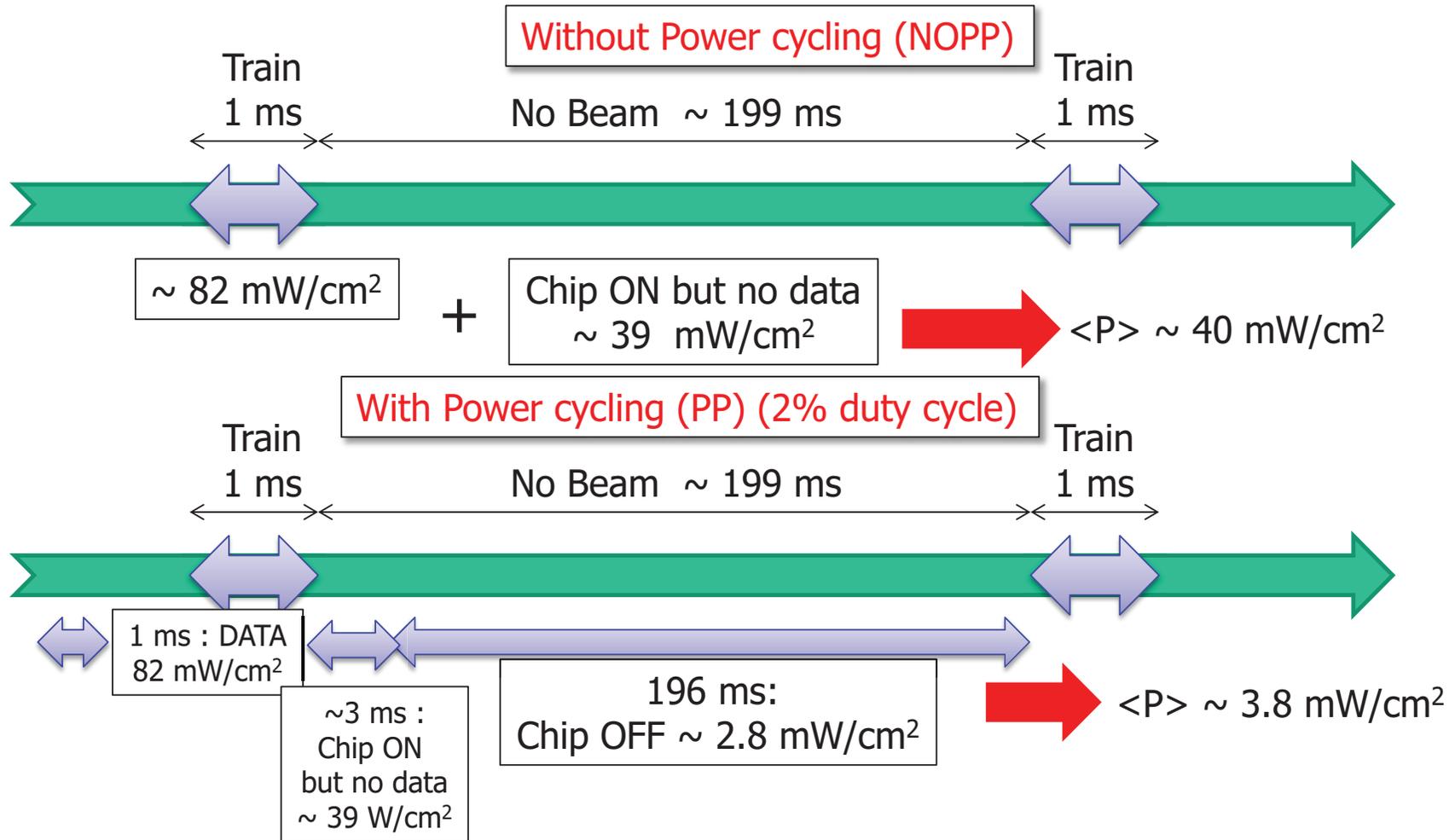
- * pixel array μ circuitry validated at $5 \mu s$
- * measured rad.tol.: 10 MRad, 10^{14} n_{eq}/cm²

- Step-2: MIMOSIS-1 full size proto.

- ⇒ back from fab. in June

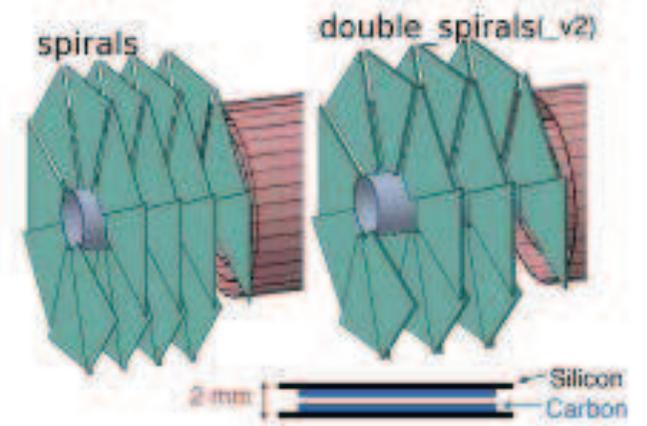
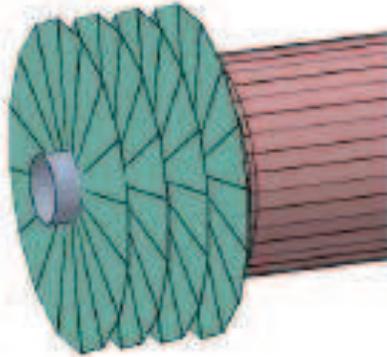


Power scheme for VTX-ILD (inner layer)

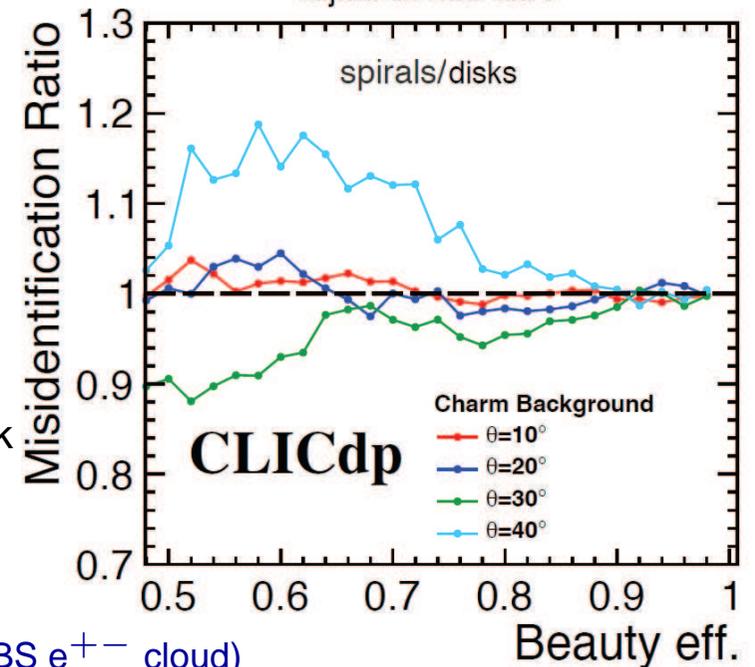


Hypothesis: 3 double sided layers (3483 cm^2), PSIRA architecture ($4 \mu\text{s} / 4 \mu\text{m}$),
 TDR background @ $\sqrt{s} = 500 \text{ GeV}$, no safety factor

Issue: Link to Forward Tracking System



Dijets at 200 GeV



- Cooling pipes introduce dead material near the IP
 \Rightarrow alternative (CLICdp approach) : cooled air flowing from outside through end-cap tracking sub-system & traversing vertex detector volume
(see N. Alipour Tehrani & P. Roloff, "Optimisation studies for the CLIC vertex-detector geometry", CLICdp-Note-2014-002).
- "40° corner":
 b-tagging impacted by increased $\langle \text{distance} \rangle$ from barrel edge to 1st disk
 c-tagging suspected to be significantly more impacted: how much ?
- Other delicate areas:
 - * near the beam pipe (cone ?) \Rightarrow minimal polar angle intercepted (fct of outgoing BS e^{+-} cloud)
 - * distance between barrel end and first forward disk \Rightarrow impact on small polar angle tagging

Issue: σ_{sp} & Δ_t in same sensor

SPATIAL RESOLUTION :

- Target value: $\lesssim 5$ to $3 \mu m$

- Function of pixel pitch

× signal charge sharing

× charge amplitude

× charge encoding (nb of bits, SNR)

Ex: $25 \mu m$ pitch × $M_{clus} = 1$ (full depletion, $\theta \sim 90^\circ$)

$$\Rightarrow \sigma_{sp} \simeq 7 \mu m !$$

- Correlation with read-out speed:

$\Delta_t \simeq$ few ns imposes fast charge collection

(full depletion, large collection diode, ...)

\Rightarrow charge sharing suppressed

- Tension mitigated IF $\Delta_t \gtrsim 100$ ns

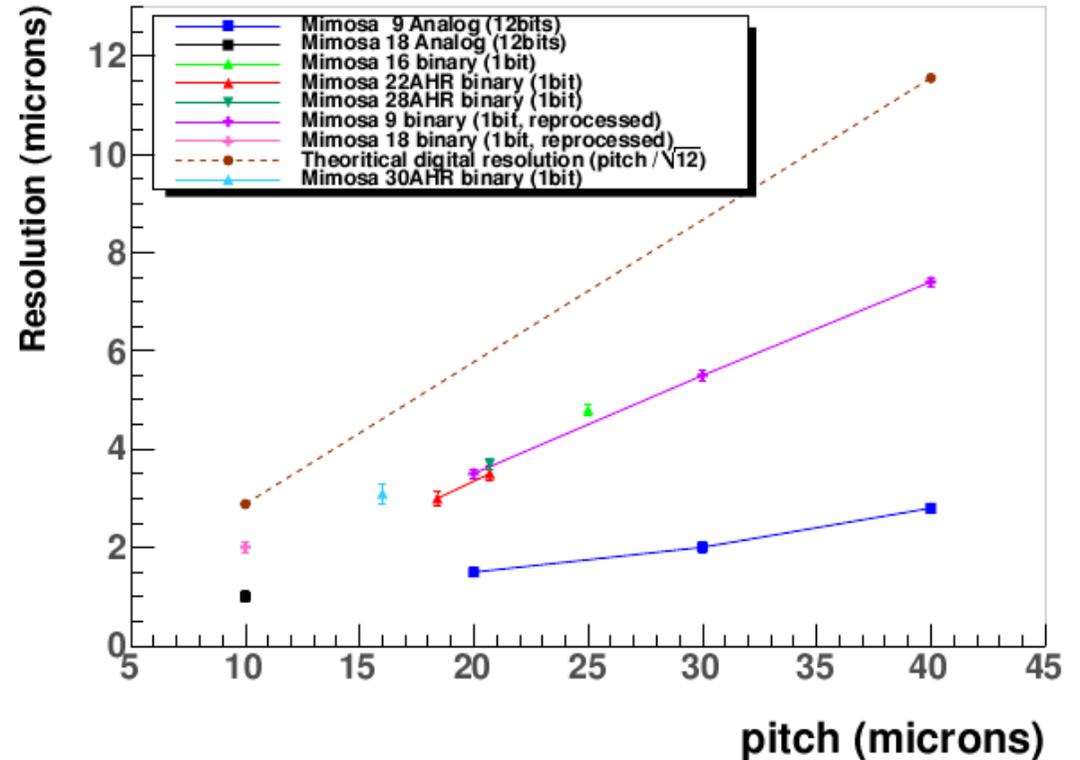
TIME STAMPING :

- mainly dictated by beam related background rate (similar at ILC & FCCee)

- $\sigma_t \lesssim 1 \mu s \Rightarrow$ hit rate \sim few $10^{-4}/cm^2/s$ × safety factor (e.g. 3-5)

\Rightarrow pixel array occupancy $\sim O(10^{-3})$ at ILC250 & FCCee \Rightarrow Affordable !

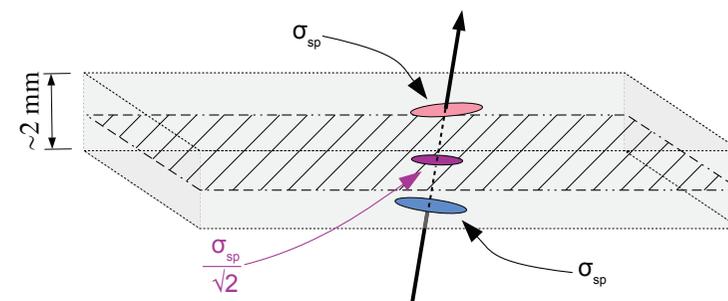
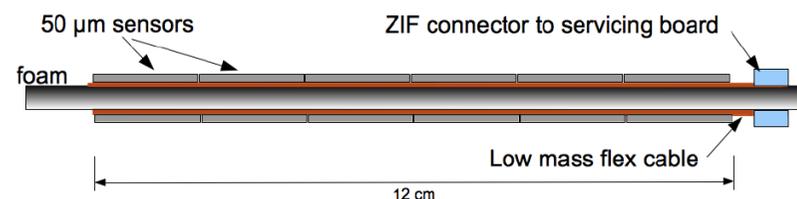
Mimosa resolution vs pitch



Ultra-Light Double-Sided Pixelated Tracker Modules

General remarks:

- Double-sided ladders for
 - excellent spatial resolution (granularity, face-to-face correlation)
 - coping with very high hit densities (speed, face-to-face correlation)
- Caveate: material budget oughts to be suppressed enough
- PLUME \equiv Existing prototype, based on MIMOSIS:
 - 8 million pixels, $\gtrsim 3 \mu m$, $115 \mu s$, $0.4 \% X_0$
- 1st goal: improve r.o. speed to $O(1) \mu s$ & squeeze mat. budget to $\lesssim 0.3 \% X_0$, validate face-to-face sensor correlation
- 2ry goal: investigate wireless face-to-face signal transmission
- Possibly: investigate power pulsing in mag. field ? (tbc)

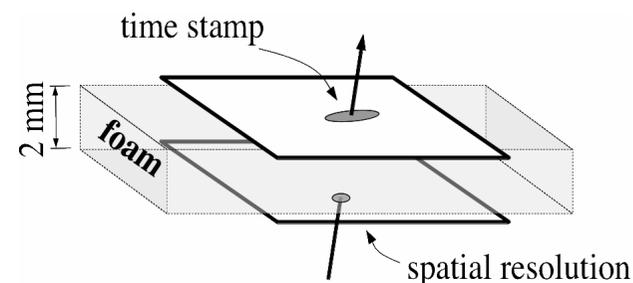


Sensor related objectives:

- Baseline MIMOSIS proto.: $\gtrsim 4 \mu m$ (tbc), $\lesssim 5 \mu s$, $\lesssim 50 \text{ mW/cm}^2$, $\gtrsim 50 \text{ MHz/cm}^2$
- Assess spatial resolution of ladder based on face-to-face correlations
- Ideally: develop mixed MALTA-MIMOSIS ladders (complicated !)

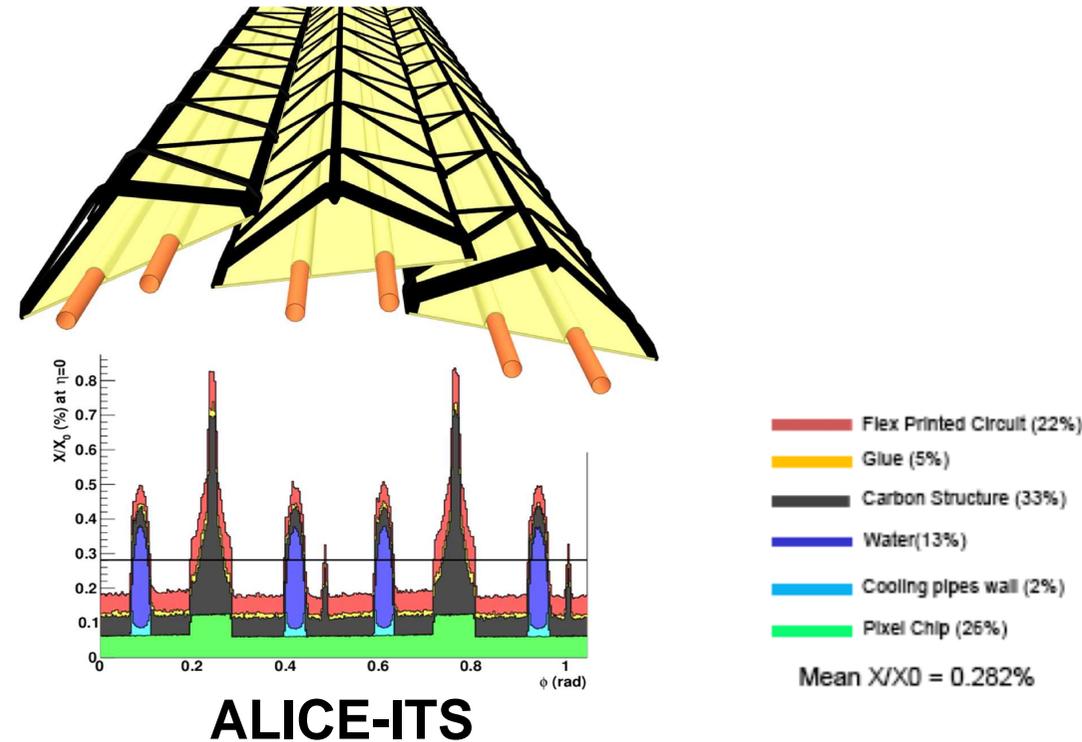
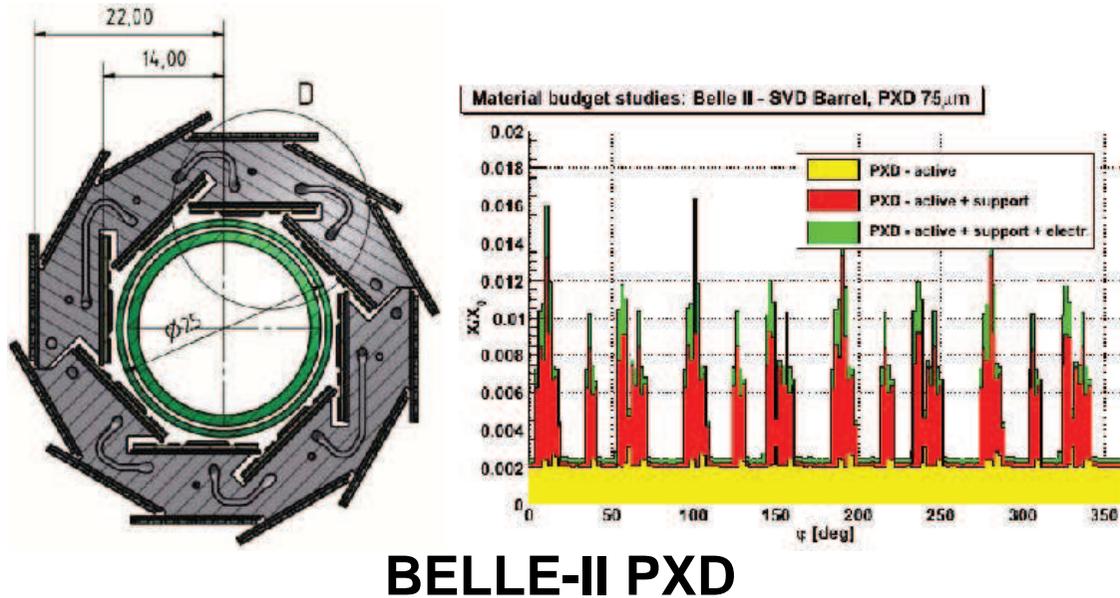
System related objectives:

- revisit structure of PLUME to compress its material budget
- investigate new materials & micro-channel cooling



Objectives of R&D in coming Years: Material budget reduction

- Physics perfo. limited by material budget of services & overlaps of neighbouring modules/ladders

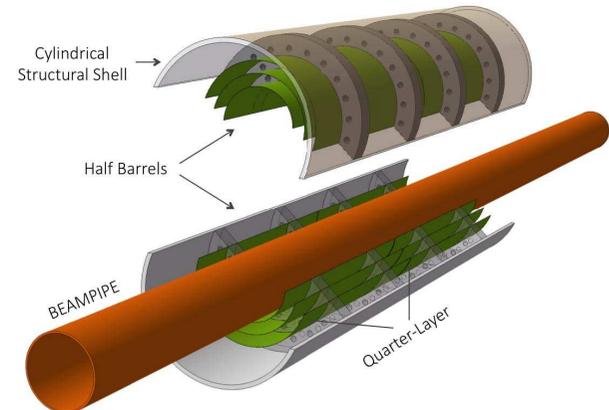


- Contribution of sensors to total material budget of vertex detector layer is modest: 15 - 30%

R&D objective beyond TDR/DBD concepts:

- Innermost layer: try stitched & curved CPS along goals of ALICE-ITS3, possibly with 65 nm process
- Concept with minimised mechanical support

(e.g. using beam pipe) See Talk of M. Mager at Vertex-19, Lopud Island, Oct.'19



SUMMARY & CONCLUSIONS

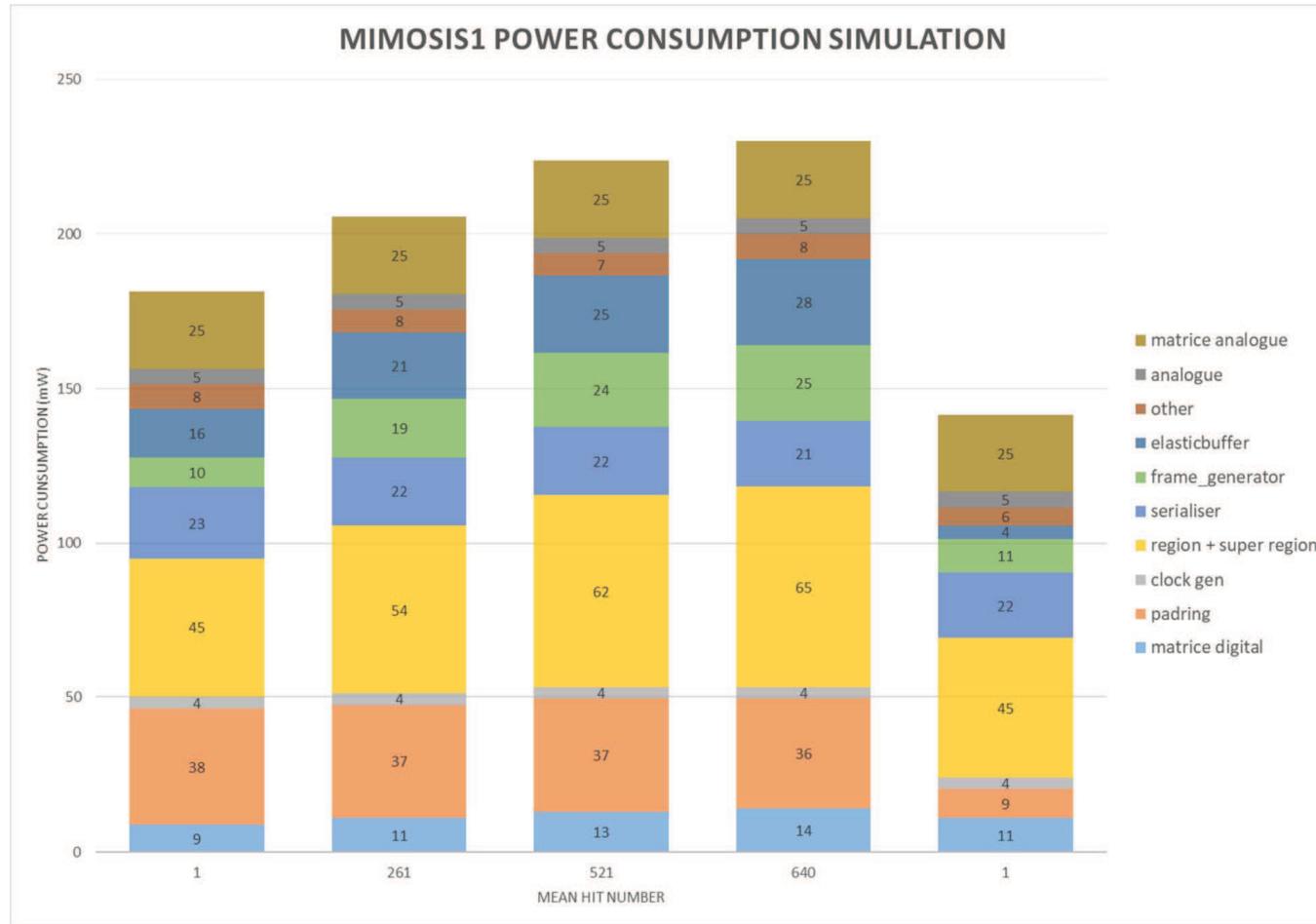
- Outcome of extensive ILC oriented R&D offers quite well defined starting point for the design of a vertex detector suited to Higgs physics at FCCee
- The sensor technology and system integration issues have similar degree of maturity
⇒ next development steps should address comprehensively all aspects of the vertex detector: geometry vs vertexing & tracking issues, mechanics, powering, signal transmission, sensors, ...)
- Industrial CMOS ASIC technology provides well suited granular & thin pixel sensors for an ILC vertex detector, exploiting the beam time structure to achieve power saving complying with air cooling
- Achieved performances still call for improvement, which may profit from attractive perspectives anticipated from industry ⇒ smaller pixels, wafer-scale sensors, power saving, ..., 2-tier sensors ?
- Adapting ILC-CPS to FCCee (continuous beam) ⇒ R&D on power saving or innovative cooling
- The concept of 2-sided detector module, which allows in particular to alleviate the conflict between ambitionned spatial resolution & read-out speed, is of common interest for FCCee and ILC
→ evolve double-sided PLUME ladders using forthcoming MIMOSIS sensor and beyond
- Defining optimal detector design for each collider requires detailed simulation & engineering studies based on same tools & expertise ⇒ opportunity for shared effort

Power Consumption of MIMOSIS-1 (1/2)

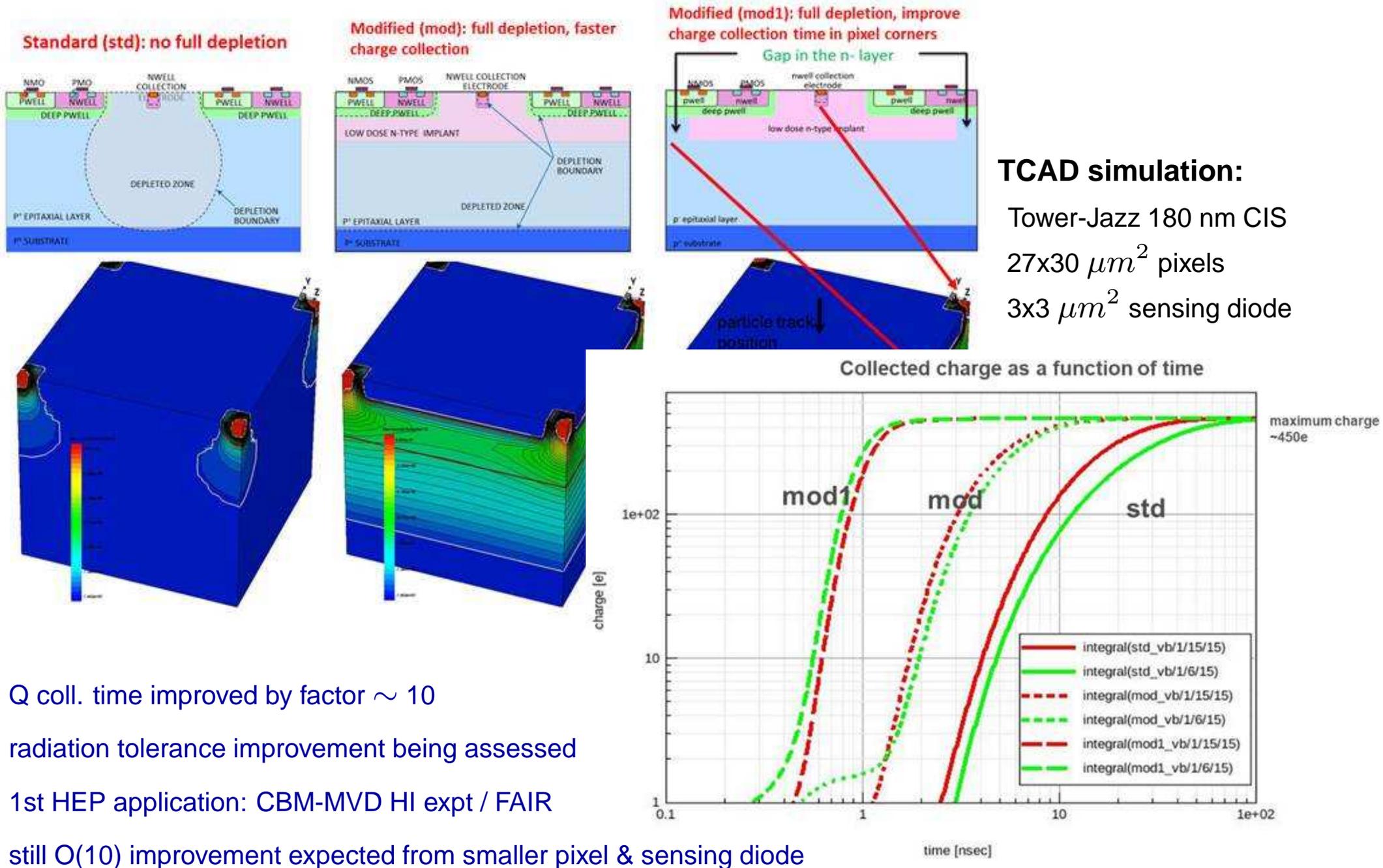
- Analogue Power: 30 mW (analogue pixel+PLL+DAC+ analogue buffers)
- Total Power = Analogue Power + Digital Power
- Total Power Density 1= Total Power/5.33 cm² (total surface)
- Total Power Density 2= Total Power/4.20 cm² (active surface)
- Power consumption with 8 outputs

	1 pixel/frame	~260 pixels/frame	~520 pixels/frame	~640 pixels/frame	1 pixel/frame 2 outputs
Digital Power mW	150	175	195	200	110
Total Power mW	180	205	225	230	140
Total Power Density 1 mW/cm ²	34	39	42	43	27
Total Power Density 2 mW/cm ²	43	49	53	55	34

Power Consumption of MIMOSIS-1 (2/2)



MIMOSIS Spin-Off: Starting Material Options



- Q coll. time improved by factor ~ 10
- radiation tolerance improvement being assessed
- 1st HEP application: CBM-MVD HI expt / FAIR
- still O(10) improvement expected from smaller pixel & sensing diode